TOSHIBA

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2020-2-27 Rev.2.0

RD Number: RD123

RD Title: TB67S209FTG Evaluation circuit BOM

Item No.	Designator	Quantity	Value	Part Number	Manufacturer	Description	Package	Not Mount
1	C_VCC	1	0.1µF 100V	-	-	Capacitor		
2	C_VM2	1	0.1µF 100V	-	-	Capacitor		
3	C_VRFA	0	0.1µF 100V	-	-	Capacitor		√
4	C_VRFB	1	0.1µF 100V	-	-	Capacitor		
5	C_VM1	1	100µF 50V	-	-	Electrolytic capacitor		
6	C_VDD	1	10µF 25V	-	-	Electrolytic capacitor		
7	C_OSCM	0	Socket pin	-	-	Socket pin		√
8		0	270pF	-	-	Leaded capacitor		√
9		1	270pF 1000V	-	-	Capacitor		
10	C_OAP	0	Not mount	-	-	Capacitor		√
11	C_OAM	0	Not mount	-	-	Capacitor		√
12	C_OBM	0	Not mount	-	-	Capacitor		√
13	C_OBP	0	Not mount	-	-	Capacitor		√
14	CON1	1	Connector 4P	-	-	Connector 4P-2.5		
15	CON2	0	Connector 2P	-	-	Connector 2P-2.5		√
16	CON3	0	Connector 2P	-	-	Connector 2P-2.5		√
17	CON4	0	Connector 3P	-	-	Connector 3P-2.5		√
18	CON5	0	Connector 3P	-	-	Connector 3P-2.5		√
19	OUT_A-	1	Check terminal	-	-	Logic pin		
20	OUT_A+	1	Check terminal	-	-	Logic pin		
21	OUT_B-	1	Check terminal	-	-	Logic pin		
22	OUT_B+	1	Check terminal	-	-	Logic pin		
23	RSA	1	Check terminal	-	-	Check terminal		
24	RSB	1	Check terminal	-	-	Check terminal		
25	VCC	1	Check terminal	-	-	Check terminal		
26	VDD	1	Check terminal	-	-	Check terminal		

27	VM	1	Check terminal	-	-	Logic pin	
28	LO	1	Check terminal	-	-	Check terminal	
29	DMODE0	1	Check terminal	-	-	Check terminal	
30	VREF	1	Check terminal	-	-	Check terminal	
31	SMD0	1	Check terminal	-	-	Logic pin	
32	SMD1	1	Check terminal	-	-	Logic pin	
33	OSCM	1	Check terminal	-	-	Check terminal	
34	CW/CCW	1	Check terminal	-	-	Check terminal	
35	МО	1	Check terminal	-	-	Check terminal	
36	DMODE1	1	Check terminal	-	-	Check terminal	
37	DMODE2	1	Check terminal	-	-	Check terminal	
38	CLK	1	Check terminal	-	-	Check terminal	
39	ENABLE	1	Check terminal	-	-	Check terminal	
40	RESET	1	Check terminal	-	-	Check terminal	
41	GND1	1	Check terminal	-	-	Logic pin	
42	GND2	1	Check terminal	-	-	Logic pin	
43	GND3	1	Check terminal	-	-	Logic pin	
44	GND4	1	Check terminal	-	-	Logic pin	
45	GND5	1	Check terminal	-	—	Logic pin	
46	GND6	1	Check terminal	-	—	Logic pin	
47	GND7	1	Check terminal	_	_	Logic pin	
48	JP_VRF1	0	Pin header 2P	_	_	Jumper	\checkmark
49		0	Jumper socket	_	_	Short pin	\checkmark
50	JP_VRF2	1	Pin header 2P	_	_	Jumper	
51		1	Jumper socket	_	_	Short pin	
52	JP_VCC	1	Pin header 2P	_	_	Jumper	
53		1	Jumper socket	_	_	Short pin	
54	R_ID	0	100kΩ 0.25W	-	-	Leaded resistor	√
55	R_MOUT	1	100kΩ 0.25W	-	-	Leaded resistor	
56	R_LOUT	1	100kΩ 0.25W	-	-	Leaded resistor	
57	R_OSCM	0	Socket pin	-	-	Socket pin	\checkmark
58	R_OSCM	0	5.1kΩ	-	-	Leaded resistor	√
59	R_OSCM	1	5.1kΩ 0.25W	-	-	Chip resistor	
60	R_VRF1	2	Socket pin	-	-	Socket pin	

61		0	Not mount	_	-	Leaded resistor		\checkmark
62	R_VRF2	2	Socket pin	-	-	Socket pin		
63		0	Not mount	-	-	Leaded resistor		\checkmark
64	R_RSA	1	0.22Ω 1W	-	-	Chip resistor		
65	R_RSB	1	0.22Ω 1W	-	-	Chip resistor		
66	CLK	0	Pin header 3P	-	-	Jumper		\checkmark
67		0	Jumper socket	-	-	Short pin		\checkmark
68	ENABLE	1	Pin header 3P	-	-	Jumper		
69		1	Jumper socket	-	-	Short pin		
70	RESET	1	Pin header 3P	-	-	Jumper		
71		1	Jumper socket	-	-	Short pin		
72	SMD0	1	Pin header 3P	-	-	Jumper		
73		1	Jumper socket	-	-	Short pin		
74	DMODE0	1	Pin header 3P	-	-	Jumper		
75		1	Jumper socket	_	—	Short pin		
76	SMD1	1	Pin header 3P	_	_	Jumper		
77		1	Jumper socket	-	-	Short pin		
78	CW/CCW	1	Pin header 3P	-	-	Jumper		
79		1	Jumper socket	-	_	Short pin		
80	МО	0	Pin header 3P	_	—	Jumper		\checkmark
81		0	Jumper socket	_	_	Short pin		\checkmark
82	DMODE1	1	Pin header 3P	_	_	Jumper		
83		1	Jumper socket	_	_	Short pin		
84	DMODE2	1	Pin header 3P	-	-	Jumper		
85		1	Jumper socket	-	_	Short pin		
86	IC1	1	TB67S209FTG	TB67S209FTG	TOSHIBA	Motor driver IC	QFN48	

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